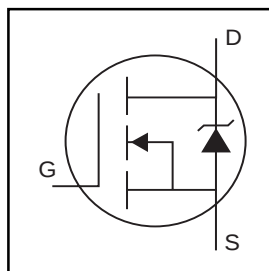


- Advanced Process Technology
- Optimized for 4.5V-7.0V Gate Drive
- Ideal for CPU Core DC-DC Converters
- Fast Switching

### Description

These HEXFET Power MOSFETs were designed specifically to meet the demands of CPU core DC-DC converters in the PC environment. Advanced processing techniques combined with an optimized gate oxide design results in a die sized specifically to offer maximum efficiency at minimum cost.

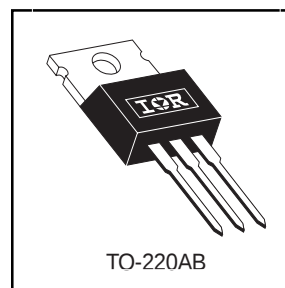
The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 watts. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



$$V_{DSS} = 20V$$

$$R_{DS(on)} = 0.013\Omega$$

$$I_D = 61A$$



### Absolute Maximum Ratings

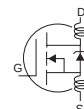
|                             | Parameter                                                         | Max.                                         | Units |
|-----------------------------|-------------------------------------------------------------------|----------------------------------------------|-------|
| $I_D$ @ $T_C = 25^\circ C$  | Continuous Drain Current, $V_{GS}$ @ 4.5V                         | 61                                           | A     |
| $I_D$ @ $T_C = 100^\circ C$ | Continuous Drain Current, $V_{GS}$ @ 4.5V                         | 39                                           |       |
| $I_{DM}$                    | Pulsed Drain Current ①                                            | 240                                          |       |
| $P_D$ @ $T_C = 25^\circ C$  | Power Dissipation                                                 | 89                                           | W     |
|                             | Linear Derating Factor                                            | 0.71                                         | W/°C  |
| $V_{GS}$                    | Gate-to-Source Voltage                                            | $\pm 10$                                     | V     |
| $V_{GSM}$                   | Gate-to-Source Voltage<br>(Start Up Transient, $t_p = 100\mu s$ ) | 14                                           | V     |
| $E_{AS}$                    | Single Pulse Avalanche Energy②                                    | 220                                          | mJ    |
| $I_{AR}$                    | Avalanche Current①                                                | 35                                           | A     |
| $E_{AR}$                    | Repetitive Avalanche Energy①                                      | 8.9                                          | mJ    |
| $dv/dt$                     | Peak Diode Recovery $dv/dt$ ③                                     | 5.0                                          | V/ns  |
| $T_J$                       | Operating Junction and                                            | -55 to + 150                                 | °C    |
| $T_{STG}$                   | Storage Temperature Range                                         |                                              |       |
|                             | Soldering Temperature, for 10 seconds                             |                                              |       |
|                             | Mounting torque, 6-32 or M3 screw                                 | 300 (1.6mm from case )<br>10 lbf•in (1.1N•m) |       |

### Thermal Resistance

|                 | Parameter                           | Typ. | Max. | Units |
|-----------------|-------------------------------------|------|------|-------|
| $R_{\theta JC}$ | Junction-to-Case                    | —    | 1.4  | °C/W  |
| $R_{\theta CS}$ | Case-to-Sink, Flat, Greased Surface | 0.50 | —    |       |
| $R_{\theta JA}$ | Junction-to-Ambient                 | —    | 62   |       |

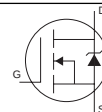
Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)

|                                 | Parameter                            | Min. | Typ.  | Max.  | Units    | Conditions                                           |
|---------------------------------|--------------------------------------|------|-------|-------|----------|------------------------------------------------------|
| $V_{(BR)DSS}$                   | Drain-to-Source Breakdown Voltage    | 20   | —     | —     | V        | $V_{GS} = 0V, I_D = 250\mu A$                        |
| $\Delta V_{(BR)DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient  | —    | 0.016 | —     | V/°C     | Reference to $25^\circ\text{C}$ , $I_D = 1mA$        |
| $R_{DS(on)}$                    | Static Drain-to-Source On-Resistance | —    | —     | 0.015 | $\Omega$ | $V_{GS} = 4.5V, I_D = 37A$ ④                         |
|                                 |                                      | —    | —     | 0.013 |          | $V_{GS} = 7.0V, I_D = 37A$ ④                         |
| $V_{GS(th)}$                    | Gate Threshold Voltage               | 0.70 | —     | —     | V        | $V_{DS} = V_{GS}, I_D = 250\mu A$                    |
| $g_{fs}$                        | Forward Transconductance             | 36   | —     | —     | S        | $V_{DS} = 16V, I_D = 35A$                            |
| $I_{DSS}$                       | Drain-to-Source Leakage Current      | —    | —     | 25    | $\mu A$  | $V_{DS} = 20V, V_{GS} = 0V$                          |
|                                 |                                      | —    | —     | 250   |          | $V_{DS} = 10V, V_{GS} = 0V, T_J = 150^\circ\text{C}$ |
| $I_{GSS}$                       | Gate-to-Source Forward Leakage       | —    | —     | 100   | nA       | $V_{GS} = 10V$                                       |
|                                 | Gate-to-Source Reverse Leakage       | —    | —     | -100  |          | $V_{GS} = -10V$                                      |
| $Q_g$                           | Total Gate Charge                    | —    | —     | 58    | nC       | $I_D = 35A$                                          |
| $Q_{gs}$                        | Gate-to-Source Charge                | —    | —     | 14    |          | $V_{DS} = 16V$                                       |
| $Q_{gd}$                        | Gate-to-Drain ("Miller") Charge      | —    | —     | 21    |          | $V_{GS} = 4.5V$ , See Fig. 6 ④                       |
| $t_{d(on)}$                     | Turn-On Delay Time                   | —    | 10    | —     | ns       | $V_{DD} = 10V$                                       |
| $t_r$                           | Rise Time                            | —    | 130   | —     |          | $I_D = 35A$                                          |
| $t_{d(off)}$                    | Turn-Off Delay Time                  | —    | 80    | —     |          | $R_G = 9.0\Omega, V_{GS} = 4.5V$                     |
| $t_f$                           | Fall Time                            | —    | 110   | —     |          | $R_D = 0.28\Omega$ , ④                               |
| $L_D$                           | Internal Drain Inductance            | —    | 4.5   | —     | nH       | Between lead,<br>6mm (0.25in.)                       |
| $L_S$                           | Internal Source Inductance           | —    | 7.5   | —     |          | from package<br>and center of die contact            |
| $C_{iss}$                       | Input Capacitance                    | —    | 2500  | —     | pF       | $V_{GS} = 0V$                                        |
| $C_{oss}$                       | Output Capacitance                   | —    | 1000  | —     |          | $V_{DS} = 15V$                                       |
| $C_{rss}$                       | Reverse Transfer Capacitance         | —    | 360   | —     |          | $f = 1.0MHz$ , See Fig. 5                            |



## Source-Drain Ratings and Characteristics

|          | Parameter                              | Min.                                                                        | Typ. | Max. | Units | Conditions                                                     |
|----------|----------------------------------------|-----------------------------------------------------------------------------|------|------|-------|----------------------------------------------------------------|
| $I_S$    | Continuous Source Current (Body Diode) | —                                                                           | —    | 61   | A     | MOSFET symbol showing the integral reverse p-n junction diode. |
| $I_{SM}$ | Pulsed Source Current (Body Diode) ①   | —                                                                           | —    | 240  |       |                                                                |
| $V_{SD}$ | Diode Forward Voltage                  | —                                                                           | —    | 1.3  | V     | $T_J = 25^\circ\text{C}, I_S = 37A, V_{GS} = 0V$ ④             |
| $t_{rr}$ | Reverse Recovery Time                  | —                                                                           | 59   | 88   | ns    | $T_J = 25^\circ\text{C}, I_F = 35A$                            |
| $Q_{rr}$ | Reverse Recovery Charge                | —                                                                           | 110  | 160  | nC    | $di/dt = 100A/\mu s$ ④                                         |
| $t_{on}$ | Forward Turn-On Time                   | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$ ) |      |      |       |                                                                |



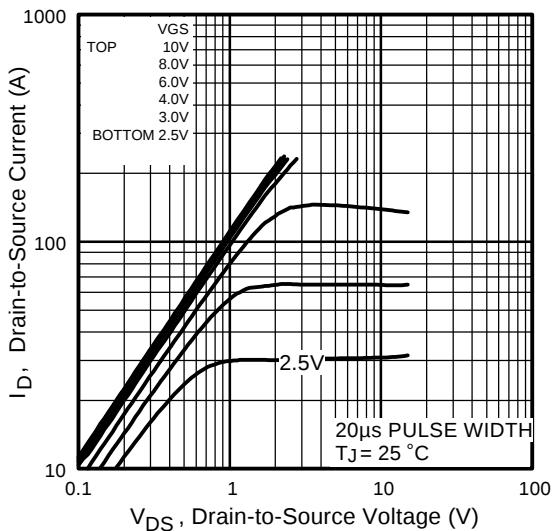
## Notes:

① Repetitive rating; pulse width limited by max. junction temperature.

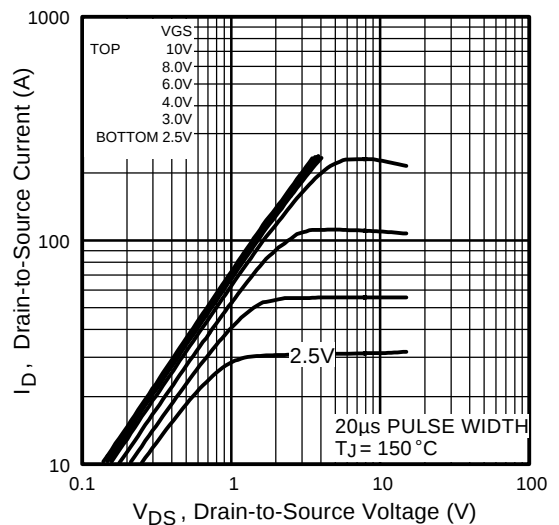
② Starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.36mH$   
 $R_G = 25\Omega$ ,  $I_{AS} = 35A$ .

③  $I_{SD} \leq 35A$ ,  $di/dt \leq 100A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  
 $T_J \leq 150^\circ\text{C}$

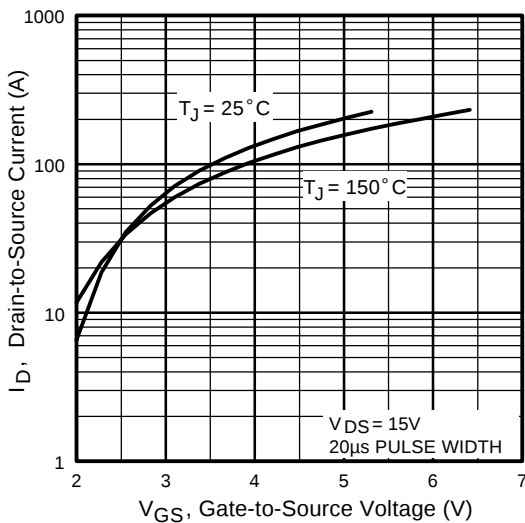
④ Pulse width  $\leq 300\mu s$ ; duty cycle  $\leq 2\%$ .



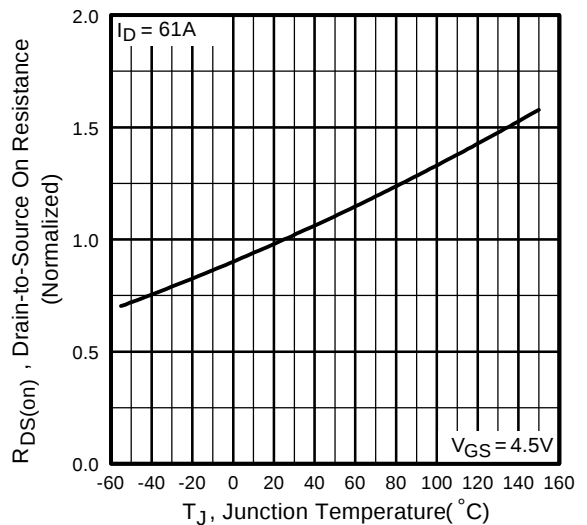
**Fig 1.** Typical Output Characteristics



**Fig 2.** Typical Output Characteristics



**Fig 3.** Typical Transfer Characteristics



**Fig 4.** Normalized On-Resistance Vs. Temperature

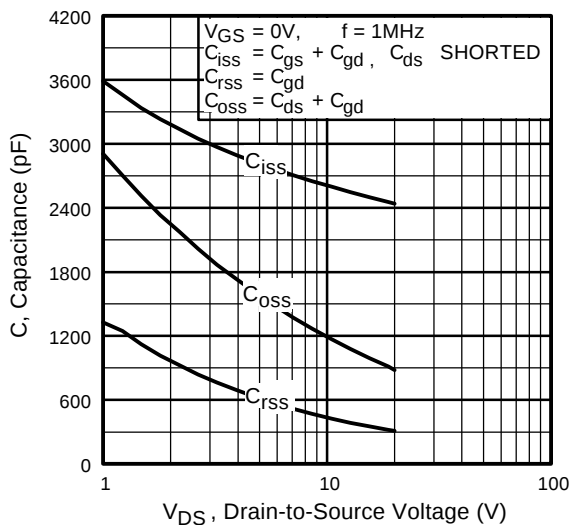


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

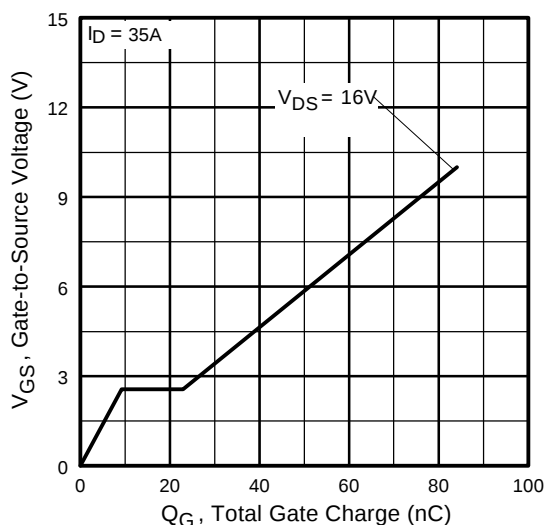


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

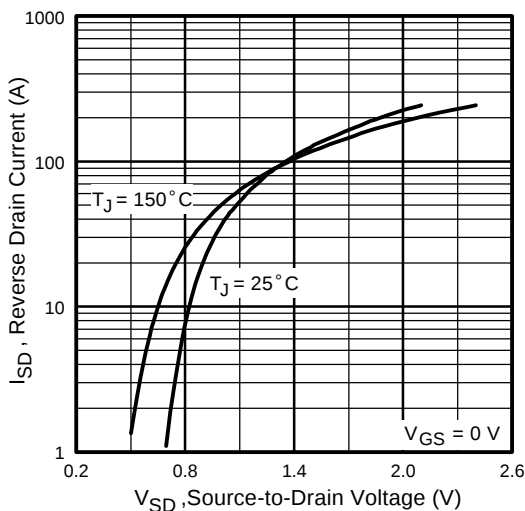


Fig 7. Typical Source-Drain Diode Forward Voltage

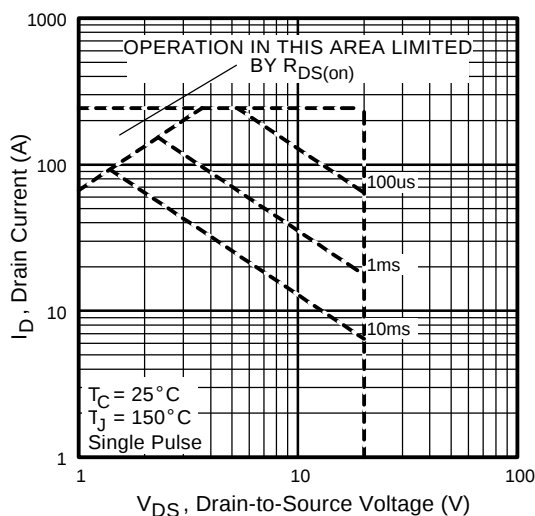
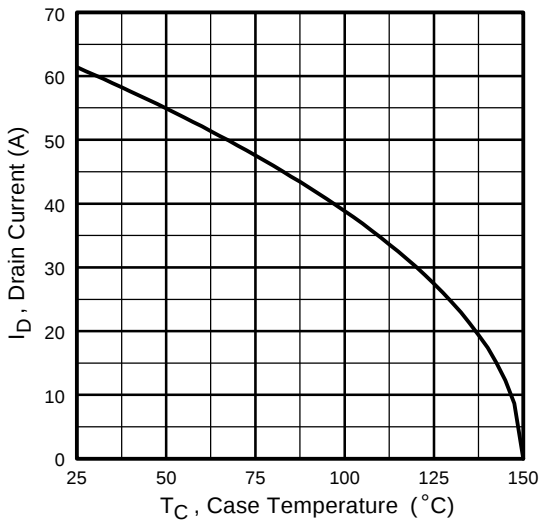
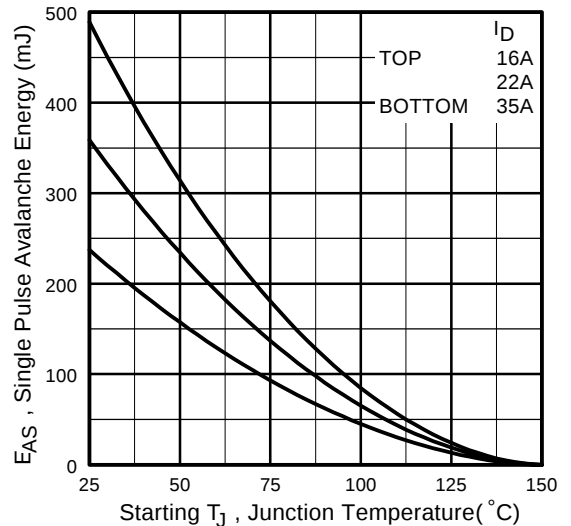


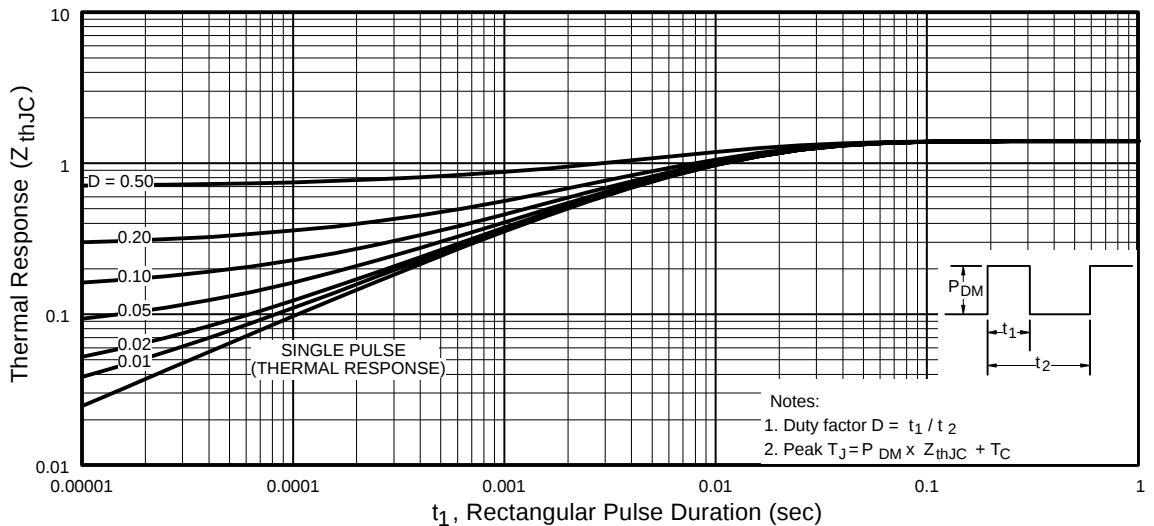
Fig 8. Maximum Safe Operating Area



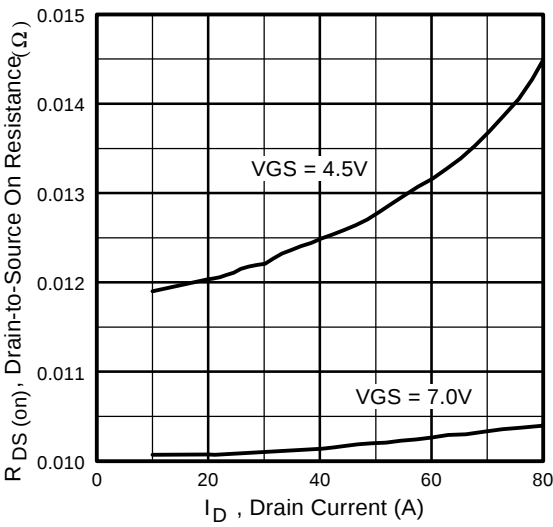
**Fig 9.** Maximum Drain Current Vs. Case Temperature



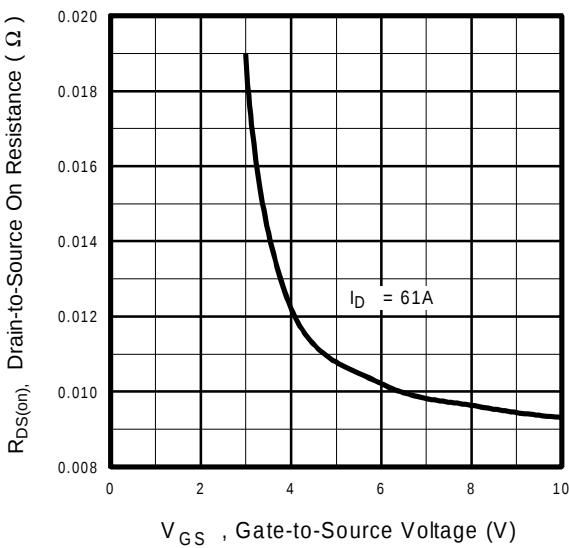
**Fig 10.** Maximum Avalanche Energy Vs. Drain Current



**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case



**Fig 12.** On-Resistance Vs. Drain Current

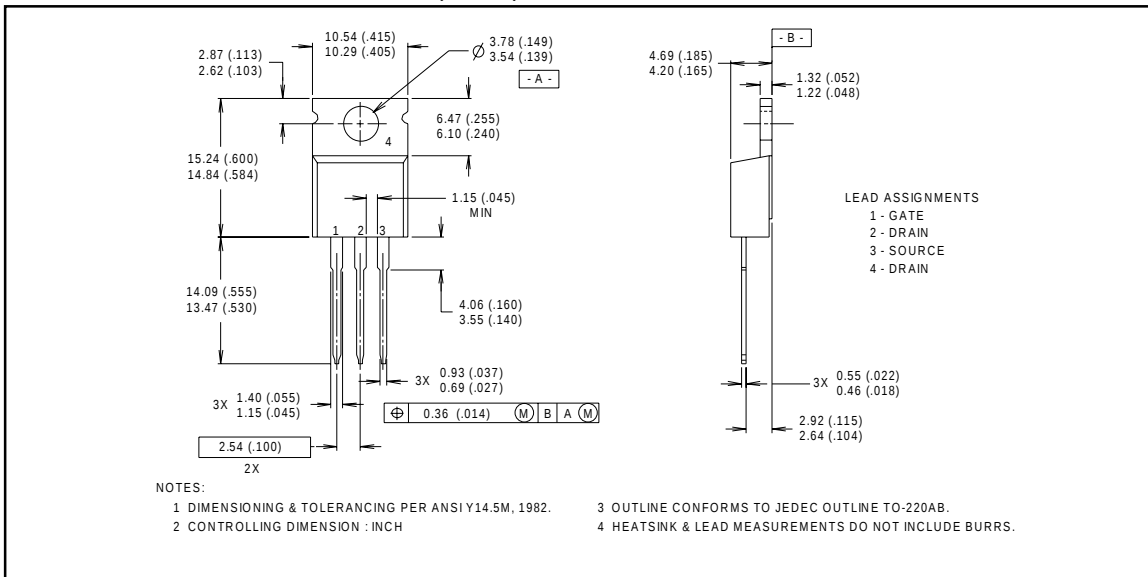


**Fig 13.** On-Resistance Vs. Gate Voltage

## Package Outline

## TO-220AB Outline

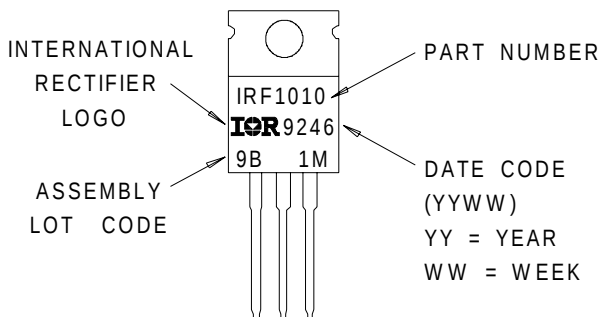
Dimensions are shown in millimeters (inches)



## Part Marking Information

**TO-220AB**

EXAMPLE: THIS IS AN IRF1010  
WITH ASSEMBLY  
LOT CODE 9B1M



**WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245, Tel: (310) 322 3331

**EUROPEAN HEADQUARTERS:** Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44 1883 732020

**IR CANADA:** 7321 Victoria Park Ave., Suite 201, Markham, Ontario L3R 2Z8, Tel: (905) 475 1897

**IR GERMANY:** Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590

**IR ITALY:** Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111

**IR FAR EAST:** K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo Japan 171 Tel: 81 3 3983 0086

**IR SOUTHEAST ASIA:** 315 Outram Road, #10-02 Tan Boon Liat Building, Singapore 0316 Tel: 65 221 8371

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